

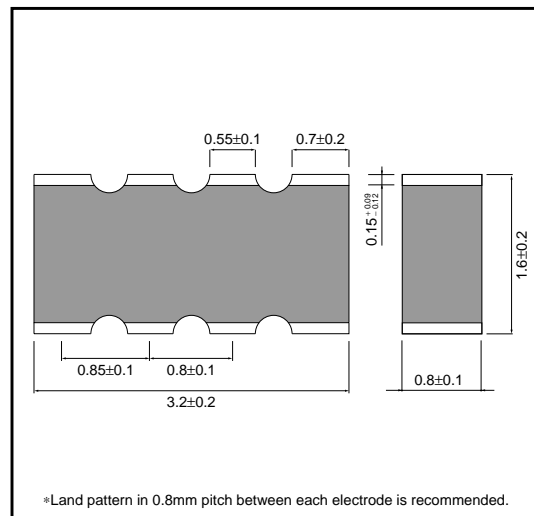
Multi-layer ceramic chip capacitor networks

MNA14 (1608 (0603) × 4 size, chip capacitor networks)

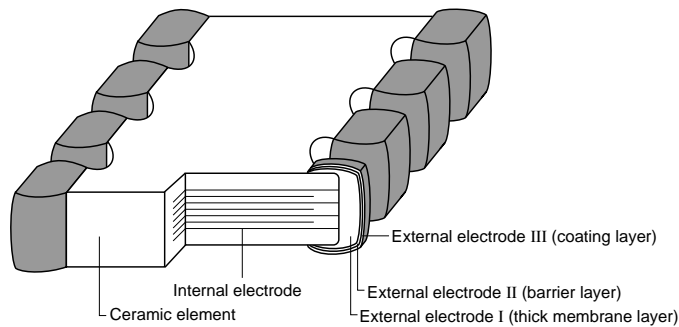
●Features

- 1) Area ratio is approximately 55% smaller than that of the MCH18, enabling high - density mounting.
- 2) Mounting costs are reduced.
- 3) Use of convex electrodes prevents solder bridging during mounting, and makes it easy to perform a visual inspection of the mounted piece. Also facilitates automatic inspection.
- 4) Barrier layer and end terminations to improve solderability.
- 5) Each element is independent to ensure a wide range of circuit applications.
- 6) Can be packed on tape.

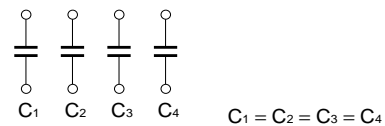
●External dimensions (Units : mm)



●Structure



●Equivalent circuits



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Ceramic capacitors

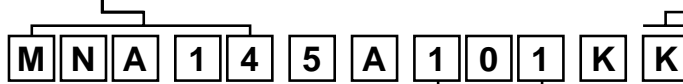
●Product designation

Code	Product thickness	Packaging specifications	Reel	Basic ordering unit (pcs.)
K	0.8mm	Paper tape (width 8 mm, pitch 4 mm)	φ180mm (7in.)	4,000

Reel (φ180mm) : compatible with EIAJ ET-7200A

Packaging style

Part No.



Rated voltage	
Code	Voltage
2	25V
5	50V

Capacitance-temperature characteristics				Nominal capacitance	Capacitance tolerance	
Code	EIA code	Operating temperature range (°C)	Temp. coefficient or percent change		Code	tolerance
A	C0G	-55 ~ +125	0 ± 30ppm / °C	3-digit designation according IEC	K	± 10%
CN	X7R	-55 ~ +125	± 15%		M	± 20%

●Capacitance range

Product name		MNA 14	
Capacitance (pF)	Temperature characteristic	A (C0G)	CN (X7R)
	Rated voltage	50V	25V
	Tolerance	K (± 10%)	M (± 20%)
10			
22			
47			
100			
220			
470			
1,000			
2,200			
4,700			
10,000			
22,000			



Product thickness (mm) 0.8 ± 0.1

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Ceramic capacitors

● Characteristics

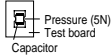

Class 1 (For thermal compensation)

Temperature characteristics		A (COG)	Test methods / conditions (based on JIS C 5102)
Item			
Operating temperature		-55°C ~ +125°C	
Nominal capacitance (C)		Must be within the specified tolerance range.	
Dissipation factor (tanδ)		100 / (400 + 20C)% or less: Less than 30 pF 0.1% or less : 30 pF or larger	Based on paragraph 7.8 and paragraph 9, Measured at room temperature and standard humidity. Measurement frequency : 1 ± 0.1MHz Measurement voltage : 1 ± 0.1Vrms.
Insulation resistance (IR)		10,000MΩ or 500MΩ·μF, whichever is smaller	Based on paragraph 7.6. Measurement is made after rated voltage is applied for 60 ± 5s.
Withstanding voltage		The insulation must not be damaged.	Based on paragraph 7.1. Apply 300% of the rated voltage for 1 to 5s then measure.
Temperature characteristics		Within 0 ± 30ppm / °C	The temperature coefficients in table 12, paragraph 7.12 are calculated at 20°C and high temperature.
Terminal adherence		No detachment or signs of detachment.	Based on paragraph 8.11.2. Apply 5N for 10 ± 1s in the direction  indicated by the arrow.
Resistance to vibration	Appearance	There must be no mechanical damage.	Chip is mounted to a board in the manner shown on the right, subjected to vibration (type A in paragraph 8.2), and measured 24 ± 2 hours later. 
	Rate of capacitance change	Must be within initial tolerance.	
	Dissipation factor (tanδ)	Must satisfy initial specified value.	
Solderability		At least 3/4 of the surface of the two terminals must be covered with new solder.	Based on paragraph 8.13. Soldering temperature : 235 ± 5°C Soldering time : 2 ± 0.5s
Resistance to soldering heat	Appearance	There must be no mechanical damage.	Based on paragraph 8.14. Soldering temperature : 260 ± 5°C Soldering time : 5 ± 0.5s Preheating : 150 ± 10°C for 1 to 2 min.
	Rate of capacitance change	± 2.5% or ± 0.25 pF, whichever is larger	
	Dissipation factor (tanδ)	Must satisfy initial specified value.	
	Insulation resistance	10,000MΩ or 500MΩ·μF, whichever is smaller	
	Withstanding voltage	The insulation must not be damaged.	
Temperature cycling	Appearance	There must be no mechanical damage.	Based on paragraph 9.3, Number of cycles : 5 Capacitance measured after 24 ± 2 hrs.
	Rate of capacitance change	± 2.5% or ± 0.25 pF, whichever is larger	
	Dissipation factor (Tanδ)	Must satisfy initial specified value.	
	Insulation resistance	10,000MΩ or 500MΩ·μF, whichever is smaller	
Humidity load test	Appearance	There must be no mechanical damage.	Based on paragraph 9.9, Test temperature : 40 ± 2°C Relative humidity : 90% to 95% Applied voltage : rated voltage Test time : 500 to 524 hrs. Capacitance measured after 24 ± 2 hrs.
	Rate of capacitance change	± 7.5% or ± 0.75 pF, whichever is larger	
	Dissipation factor (tanδ)	0.5% or less	
	Insulation resistance	500MΩ or 25MΩ·μF, whichever is smaller	
High-temperature load test	Appearance	There must be no mechanical damage.	Based on paragraph 9.10, Test temperature : Max. operating temp. Applied voltage : rated voltage × 200% Test time : 1,000 to 1,048 hrs. Capacitance measured after 24 ± 2 hrs.
	Rate of capacitance change	± 3.0% or ± 0.3 pF, whichever is larger	
	Dissipation factor (tanδ)	0.3% or less	
	Insulation resistance	10,000MΩ or 50MΩ·μF, whichever is smaller	

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Ceramic capacitors

Class 2 (High dielectric constant)

Temperature characteristics		CN (X7R)	Test methods/conditions (based on JIS C 5102)
Operating temperature		-55°C ~ +125°C	—————
Nominal capacitance (C)		Must be within the specified tolerance range.	Based on paragraph 7.8 Measured at room temperature and standard humidity.
Dissipation factor (tanδ)		2.5% or less (when rated voltage is 16V : 3.5% or less)	Measurement frequency: 1 ± 0.1 kHz Measurement voltage : 0.1 ± 0.2 Vrms.
Insulation resistance (IR)		10,000MΩ or 500MΩ·μF, whichever is smaller	Based on paragraph 7.6 Measurement is made after rated voltage is applied for 60 ± 5s.
Withstanding voltage		The insulation must not be damaged.	Based on paragraph 7.1 Apply 250% of the rated voltage for 1 to 5s then measure.
Temperature characteristics		Within ± 15%	The temperature coefficients in paragraph 7.12, table 8, condition B, are based on measurements carried out at 20°C, with no voltage applied.
Terminal adherence		No peeling or sign of peeling on terminal.	Based on paragraph 8.11.2. Apply 5N for 10 ± 1s in the direction indicated by the arrow. 
Resistance to vibration	Appearance	There must be no mechanical damage.	Chip is mounted to a board in the manner shown on the right, subjected to vibration (type A in paragraph 8.2), and measured 48 ± 4 hrs. later. 
	Rate of capacitance change	Must be within initial tolerance.	
	Dissipation factor (tanδ)	Must satisfy initial specified value.	
Solderability		At least 3/4 of the surface of the two terminals must be covered with new solder.	Based on paragraph 8.13 Soldering temperature: 235 ± 5°C Soldering time : 2 ± 0.5s
Resistance to soldering heat	Appearance	There must be no mechanical damage.	Based on paragraph 8.14. Soldering temperature: 260 ± 5°C Soldering time : 5 ± 0.5s Preheating : 150 ± 10°C for 1 to 2 min.
	Rate of capacitance change	Within ± 5.0%	
	Dissipation factor (tanδ)	Must satisfy initial specified value.	
	Insulation resistance	10,000MΩ or 500MΩ·μF, whichever is smaller	
	Withstanding voltage	The insulation must not be damaged.	
Temperature cycling	Appearance	There must be no mechanical damage.	Based on paragraph 9.3 Number of cycles : 5 Capacitance measured after 48 ± 4 hrs.
	Rate of capacitance change	Within ± 7.5%	
	Dissipation factor (tanδ)	Must satisfy initial specified value.	
	Insulation resistance	10,000MΩ or 500MΩ·μF, whichever is smaller	
Humidity load test	Appearance	There must be no mechanical damage.	Based on paragraph 9.9 Test temperature : 40 ± 2°C Relative humidity : 90% to 95% Applied voltage : rated voltage Test time : 500 to 524 hrs. Capacitance measured after 48 ± 4 hrs.
	Rate of capacitance change	Within ± 12.5%	
	Dissipation factor (tanδ)	5.0% or less	
	Insulation resistance	500MΩ or 25MΩ·μF, whichever is smaller	
High-temperature load test	Appearance	There must be no mechanical damage.	Based on paragraph 9.10 Test temperature : Max. operating temp. Applied voltage : rated voltage × 200% Test time : 1,000 to 1,048 hrs. Capacitance measured after 48 ± 4 hrs.
	Rate of capacitance change	Within ± 10.0%	
	Dissipation factor (tanδ)	5.0% or less	
	Insulation resistance	1,000MΩ or 50MΩ·μF, whichever is smaller	

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Ceramic capacitors

●Packaging specifications

(Units : mm)

Taping										Reel	
Symbol	C	D	E	F	G	H	J	t	t1		
Dimensions	8.0 ±0.3	3.5 ±0.05	1.75 ±0.1	4.0 ±0.1	2.0 ±0.05	4.0 ±0.1	φ1.5 ^{+0.1}	1.05 MAX.	1.2 MAX.		
Size	Symbol	A	B								
	1608 × 4	2.0 ±0.1	3.5 ±0.1								
										<p>Label position</p> <p>(φ180mm reel)</p> <p>EIAJ ET-7200A compliant</p>	

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Ceramic capacitors

● Electrical characteristics

■ A (C0G) Characteristics

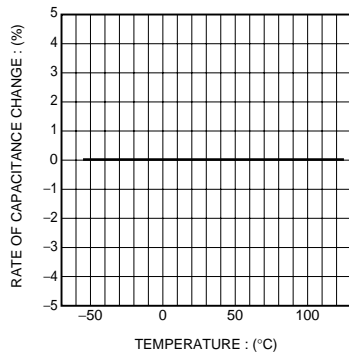


Fig.1 Capacitance-temperature characteristics

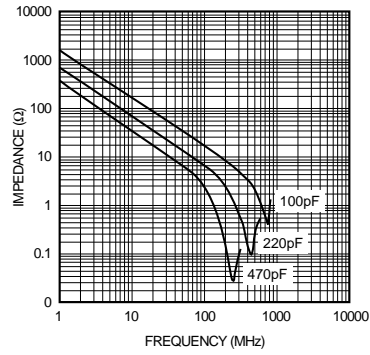


Fig.2 Impedance-frequency characteristics

■ CN (X7R) Characteristics

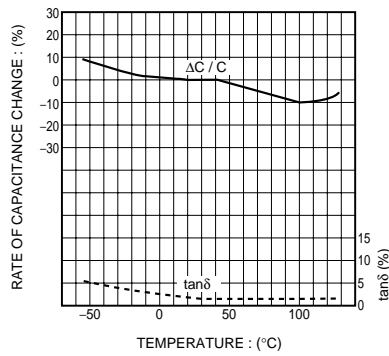


Fig.3 Capacitance-temperature characteristics

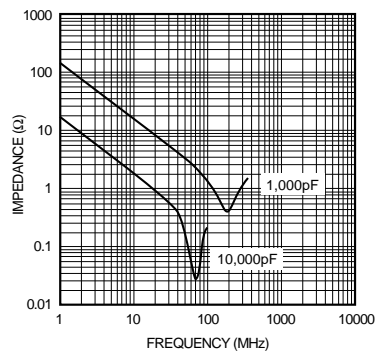


Fig.4 Impedance-frequency characteristics

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Ceramic capacitors

Temperature cycling test

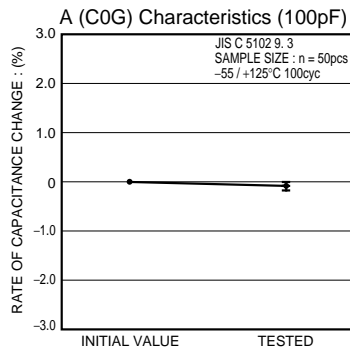


Fig.5 Rate of capacitance change

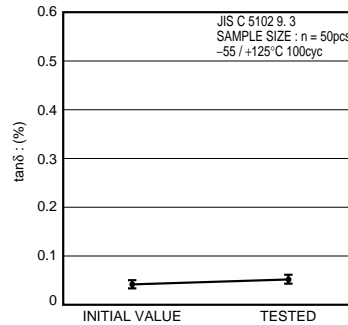


Fig.6 tanδ

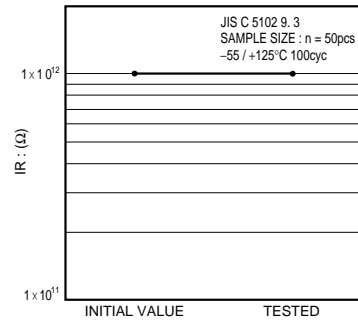


Fig.7 Insulation resistance

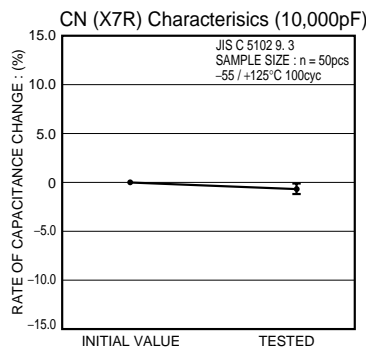


Fig.8 Rate of capacitance change

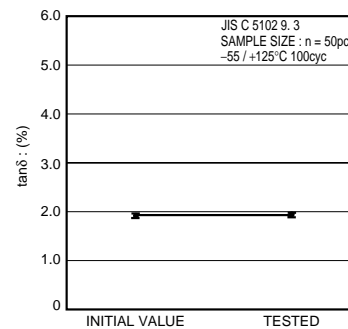


Fig.9 tanδ

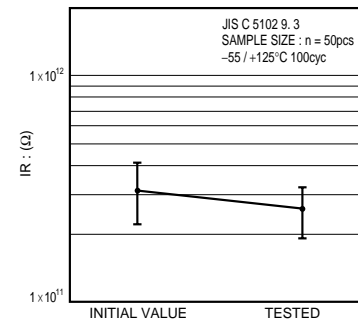


Fig.10 Insulation resistance

High – temperature load test

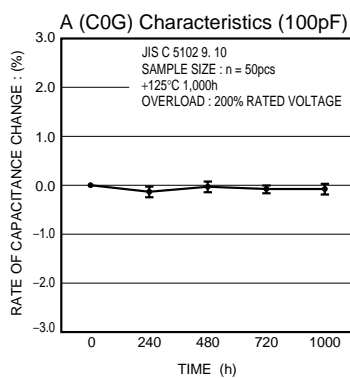


Fig.11 Rate of capacitance change

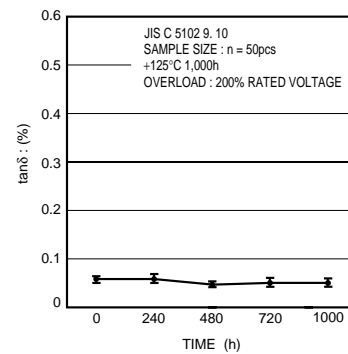


Fig.12 tanδ

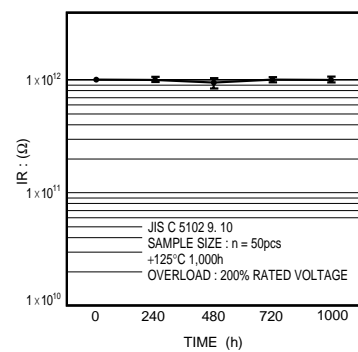


Fig.13 Insulation resistance

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Ceramic capacitors

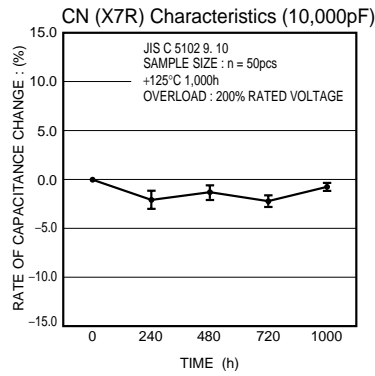


Fig.14 Rate of capacitance change

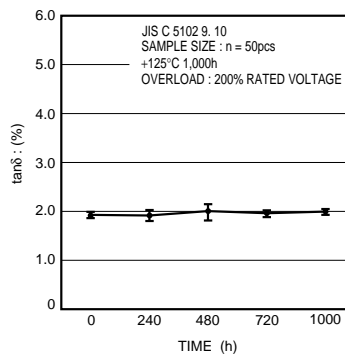


Fig.15 tanδ

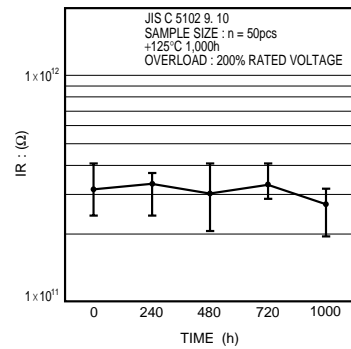


Fig.16 Insulation resistance

■ Humidity load test

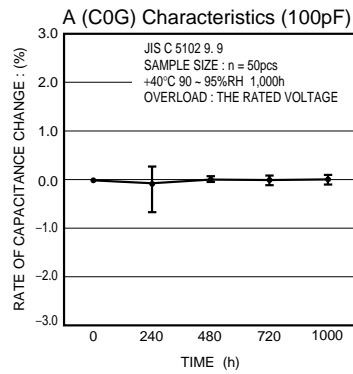


Fig.17 Rate of capacitance change

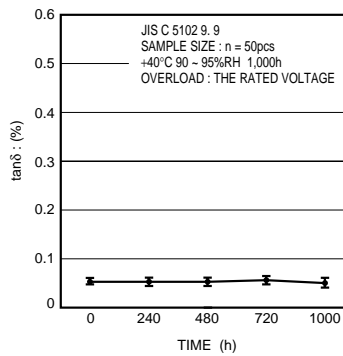


Fig.18 tanδ

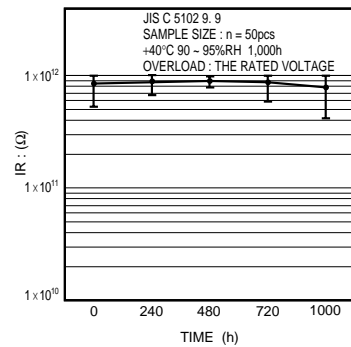


Fig.19 Insulation resistance

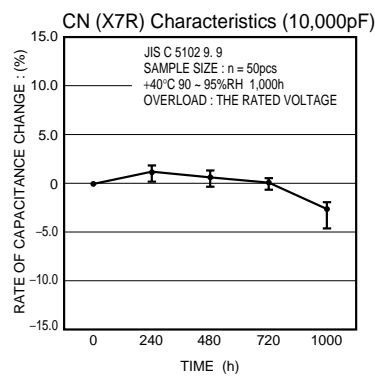


Fig.20 Rate of capacitance change

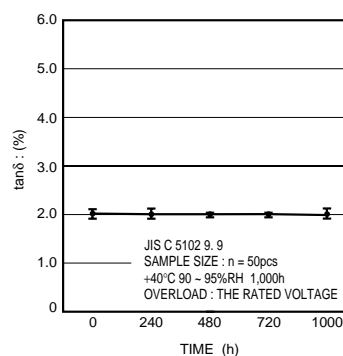


Fig.21 tanδ

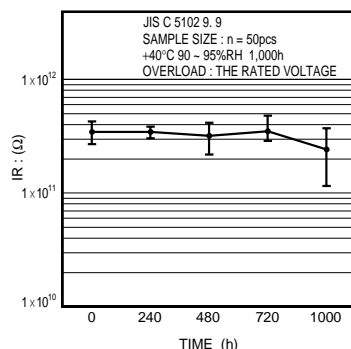


Fig.22 Insulation resistance

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